



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1403-01 DATE 3-Apr-2014		MEANS OF DISTINGUISHING CHANGED DEVICES: ☐ Product Mark ☒ Back Mark Lot# will have a "A" prefix to denote alternate site, OSE Taiwan. ☐ Date Code ☐ Other
Product Affected: SOIC-28 Refer to Attachment II for the affected part numbers		
Date Effective: 3-Jul-2014		
Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No	
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request & availability.	

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|---|
| ☐ Die Technology | This notification is to advise our customers that IDT is adding OSE, Taiwan (OSET) as an alternate assembly facility for the selective devices of the SOIC-28 package type. |
| ☐ Wafer Fabrication Process | |
| ☐ Assembly Process | |
| ☐ Equipment | |
| ☐ Material | There is no change to the moisture performance. |
| ☐ Testing | |
| ☒ Manufacturing Site | Attachment I details the qualification data for this change and Attachment II shows the affected list of part numbers. |
| ☐ Data Sheet | |
| ☐ Other | |

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____
CUSTOMER COMMENTS: _____	

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1403-01

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding OSE, Taiwan (OSET) as an alternate assembly facility for the selective devices of the SOIC-28 package type. Presently, OSET is a qualified IDT subcontractor.

The material sets used at OSET are qualified IDT materials.

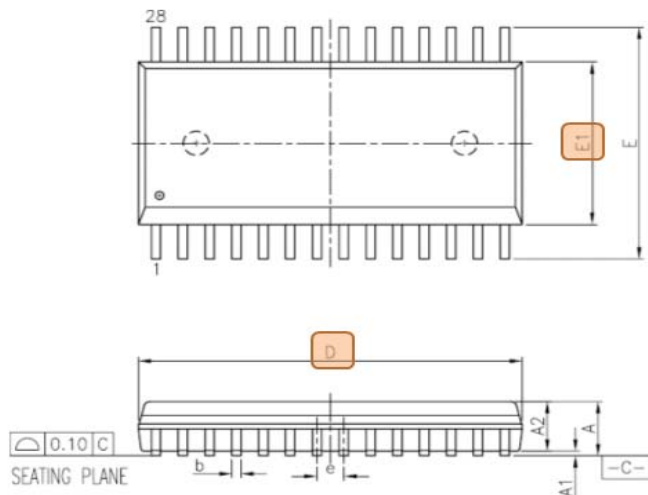
There is no change to the moisture performance of this package using the assembly material sets as listed in Table 1.

There are minor changes on the package dimensions as shown in Table 2.

Table 1: Assembly Material Sets for the Existing Assembly & Alternate Assembly

	Existing Assembly	Alternate Assembly
Material Set / Assembly	PTU - Unisem Batam, Indonesia	OSET - OSE, Taiwan
Die Attach	8390	CRM1076WA
Wire	Au wire	Au wire
Mold Compound	G600	G631

Table 2: Comparizon of Package Outline Dimensions on the Existing Assembly and Alternate Assembly



POD SYMBOL	Unisem mils	OSE mils	Jedec mils	Remarks
D (body length)	718~728	697~733	697~733	No impact to design board footprint
E1 (body width)	340~350	324~350	324~350	



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1403-01

Qualification Test Plans and Results :

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests.

Qual Vehicle: SOIC-28 (1 lot)

Test Description	Test Method	Test Results (Rej / SS)
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/30
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	0/30
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	0/30
Ball Shear Test	JESD22-B116	0/5
External Visual Inspection	JESD22-B101	0/25
Internal Visual Inspection	MIL-STD-883 (Method 2010)	0/5
X-ray Examination	IDT Spec MAC-3012	0/45
Moisture Classification (MSL 3 @ 260°C)	J-STD-020	0/25

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT II - PCN # : A1403-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
7200L12SOG	7201LA12SOG	7201LA35SOG	7202LA25SOG
7200L12SOG8	7201LA12SOG8	7201LA35SOG8	7202LA25SOG8
7200L15SOG	7201LA12SOGI	7201LA50SOG	7202LA25SOGI
7200L15SOG8	7201LA12SOGI8	7201LA50SOG8	7202LA25SOGI8
7200L15SOGI	7201LA15SOG	7202LA12SOG	7202LA35SOG
7200L15SOGI8	7201LA15SOG8	7202LA12SOG8	7202LA35SOG8
7200L20SOG	7201LA15SOGI	7202LA12SOGI	7202LA50SOG
7200L20SOG8	7201LA15SOGI8	7202LA12SOGI8	7202LA50SOG8
7200L25SOG	7201LA20SOG	7202LA15SOG	7204L12SOG
7200L25SOG8	7201LA20SOG8	7202LA15SOG8	7204L12SOG8
7200L25SOGI	7201LA20SOGI	7202LA15SOGI	7204L15SOGI
7200L25SOGI8	7201LA20SOGI8	7202LA15SOGI8	7204L15SOGI8
7200L35SOG	7201LA25SOG	7202LA20SOG	72125L25SOG
7200L35SOG8	7201LA25SOG8	7202LA20SOG8	72125L25SOG8
7200L50SOG	7201LA25SOGI	7202LA20SOGI	72125L50SOG
7200L50SOG8	7201LA25SOGI8	7202LA20SOGI8	72125L50SOG8